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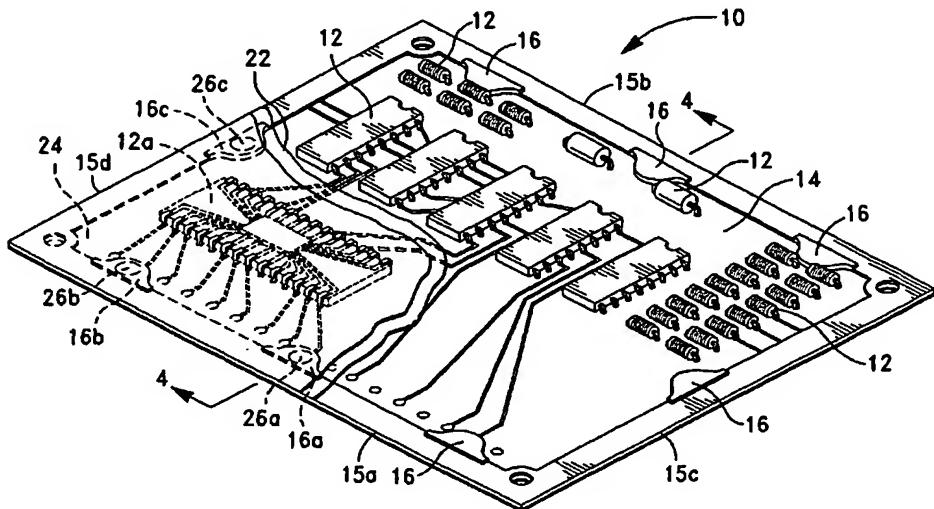
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(54) Title: METHOD AND APPARATUS FOR REDUCING ELECTROMAGNETIC EMISSIONS FROM ELECTRONIC CIRCUITS



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(57) Abstract: An electronic circuit (10) comprising at least one electrical component (12) and at least one grounding point (16) is provided that includes a first layer of non-conductive coating (18) and a second layer of conductive coating (20). The non-conductive coating (18) is applied over the electrical component (12) in such a manner that the grounding point (16) remains uncoated. The conductive coating (20) is applied over the non-conductive coating (18) and the grounding point (16) so as to ground the conductive coating (20). The conductive coating (20) thus shields the electrical component (12) to thereby reduce electromagnetic emissions from the electronic circuit (10). Various exemplary embodiments of the coated electronic circuit and associated method are provided.



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